

November 2014

FDBL0065N40

N-Channel PowerTrench[®] MOSFET 40 V, 300 A, 0.65 m Ω

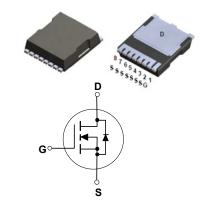
Features

- Typical $R_{DS(on)}$ = 0.5 m Ω at V_{GS} = 10V, I_D = 80 A
- Typical $Q_{q(tot)}$ = 220 nC at V_{GS} = 10V, I_D = 80 A
- UIS Capability
- RoHS Compliant

Applications

- Industrial Motor Drive
- Industrial Power Supply
- Industrial Automation
- Battery Operated tools
- Battery Protection
- Solar Inverters
- UPS and Energy Inverters
- Energy Storage
- Load Switch





For current package drawing, please refer to the Fairchild website at https://www.fairchildsemi.com/evaluate/package-specifications/packageDetails.html?id=PN_PSOFA-008

MOSFET Maximum Ratings T_J = 25°C unless otherwise noted.

Symbol	Parameter		Ratings	Units
V_{DSS}	Drain-to-Source Voltage		40	V
V_{GS}	Gate-to-Source Voltage		±20	V
1	Drain Current - Continuous (V _{GS} =10) (Note 1)	$T_C = 25^{\circ}C$	300	A
'D	Pulsed Drain Current	T _C = 25°C	See Figure 4	A
E _{AS}	Single Pulse Avalanche Energy	(Note 2)	1064	mJ
D	Power Dissipation		429	W
P_D	Derate Above 25°C		2.86	W/°C
T _J , T _{STG}	Operating and Storage Temperature		-55 to + 175	°C
$R_{\theta JC}$	Thermal Resistance, Junction to Case		0.35	°C/W
$R_{\theta JA}$	Maximum Thermal Resistance, Junction to Ambient	(Note 3)	43	°C/W

Notes:

- 1: Current is limited by bondwire configuration.
- 2: Starting $T_J = 25^{\circ}C$, L = 0.3mH, $I_{AS} = 84$ A, $V_{DD} = 40$ V during inductor charging and $V_{DD} = 0$ V during time in avalanche.
- 3: R_{0,JA} is the sum of the junction-to-case and case-to-ambient thermal resistance, where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{0,JC} is guaranteed by design, while R_{0,JA} is determined by the board design. The maximum rating presented here is based on mounting on a 1 in² pad of 2oz copper.

Package Marking and Ordering Information

Device Marking	Device	Package			
FDBL0065N40	FDBL0065N40	MO-299A	-	-	-

Units

Max.

Electrical Characteristics $T_J = 25$ °C unless otherwise noted.

Parameter

Off Ch	Off Characteristics							
B _{VDSS}	Drain-to-Source Breakdown Voltage	$I_D = 250 \mu A$,	V _{GS} = 0V	40	-	-	V	
1	Drain-to-Source Leakage Current	V _{DS} =40V,	$T_J = 25^{\circ}C$	-	-	1	μΑ	
IDSS	Dialii-to-Source Leakage Current	$V_{GS} = 0V$	$T_J = 175^{\circ}C \text{ (Note 4)}$	-	-	1	mA	
I_{GSS}	Gate-to-Source Leakage Current	$V_{GS} = \pm 20V$		1	-	±100	nA	

Test Conditions

Min.

Тур.

On Characteristics

Symbol

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$		2.0	3.0	4.0	V
D	DS(on) Drain to Source On Resistance	I _D = 80A,	$T_J = 25^{\circ}C$	-	0.50	0.65	mΩ
NDS(on)		V _{GS} = 10V	$T_J = 175^{\circ}C \text{ (Note 4)}$	-	0.86	1.10	mΩ

Dynamic Characteristics

C _{iss}	Input Capacitance	2514.14		-	15900	-	pF
C _{oss}	Output Capacitance	$V_{DS} = 25V, V_{GS} = 100$	$V_{DS} = 25V, V_{GS} = 0V,$ - f = 1MHz		4025	-	pF
C _{rss}	Reverse Transfer Capacitance	1 - 11VII 12			604	-	pF
R_g	Gate Resistance	f = 1MHz		-	2.6	-	Ω
$Q_{g(ToT)}$	Total Gate Charge at 10V	$V_{GS} = 0$ to 10V	V _{DD} = 20V	-	220	296	nC
$Q_{g(th)}$	Threshold Gate Charge	$V_{GS} = 0 \text{ to } 2V$	I _D = 80A	-	29	39	nC
Q_{gs}	Gate to Source Gate Charge		_	-	73	-	nC
Q_{gd}	Gate to Drain "Miller" Charge			-	41	-	nC

Switching Characteristics

t _{on}	Turn-On Time		-	-	221	ns
t _{d(on)}	Turn-On Delay		-	54	1	ns
t _r	Rise Time	V _{DD} = 20V, I _D = 80A,	-	82	-	ns
t _{d(off)}	Turn-Off Delay	V_{GS} = 10V, R_{GEN} = 6Ω	-	106	-	ns
t _f	Fall Time		-	52	-	ns
t _{off}	Turn-Off Time		-	ı	215	ns

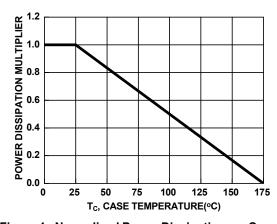
Drain-Source Diode Characteristics

V	Source to Drain Diode Voltage	I_{SD} =80A, V_{GS} = 0V	0A, V _{GS} = 0V	-	1.25	V
V_{SD}	Source to Drain Diode Voltage	I_{SD} = 40A, V_{GS} = 0V	-	-	1.2	V
t _{rr}	Reverse Recovery Time	$I_F = 80A$, $dI_{SD}/dt = 100A/\mu s$,	-	119	133	ns
Q _{rr}	Reverse Recovery Charge	V _{DD} =32V	-	228	274	nC

Note:

4: The maximum value is specified by design at T_J = 175°C. Product is not tested to this condition in production.

Typical Characteristics



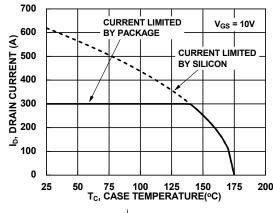


Figure 1. Normalized Power Dissipation vs. Case Temperature

Figure 2. Maximum Continuous Drain Current vs. Case Temperature

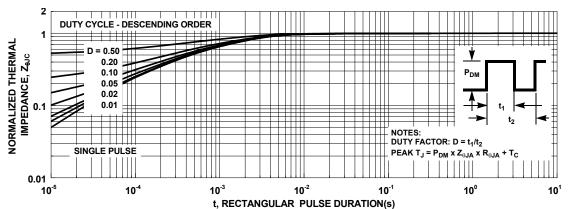


Figure 3. Normalized Maximum Transient Thermal Impedance

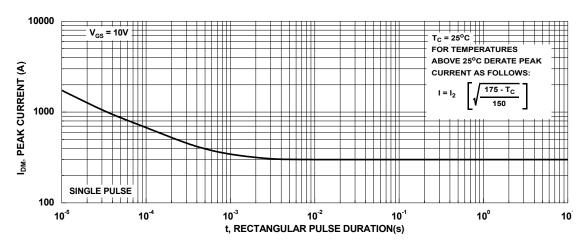


Figure 4. Peak Current Capability

Typical Characteristics

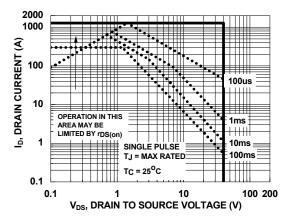
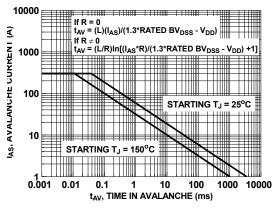


Figure 5. Forward Bias Safe Operating Area



NOTE: Refer to Fairchild Application Notes AN7514 and AN7515

Figure 6. Unclamped Inductive Switching

Capability

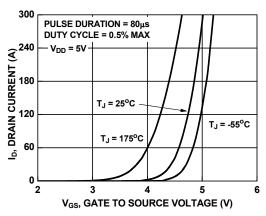


Figure 7. Transfer Characteristics

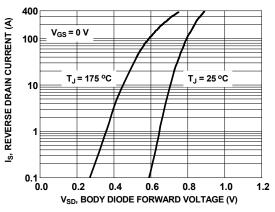


Figure 8. Forward Diode Characteristics

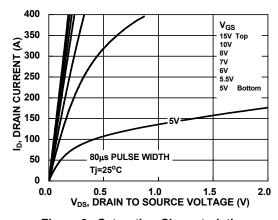


Figure 9. Saturation Characteristics

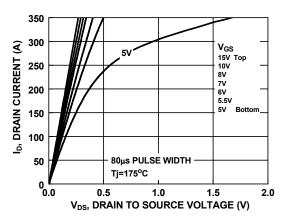


Figure 10. Saturation Characteristics

Typical Characteristics

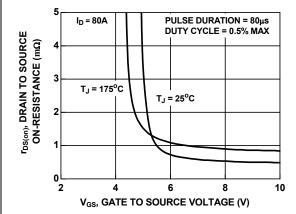


Figure 11. R_{DSON} vs. Gate Voltage

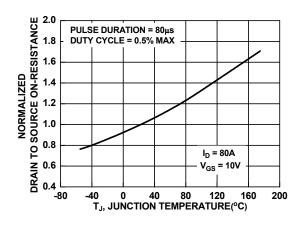


Figure 12. Normalized R_{DSON} vs. Junction Temperature

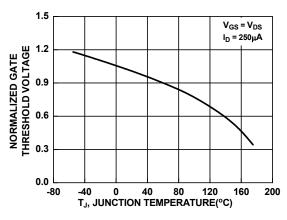


Figure 13. Normalized Gate Threshold Voltage vs. Temperature

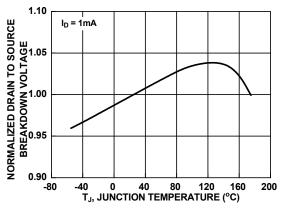


Figure 14. Normalized Drain to Source Breakdown Voltage vs. Junction Temperature

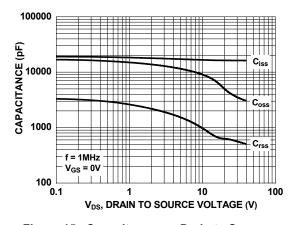


Figure 15. Capacitance vs. Drain to Source Voltage

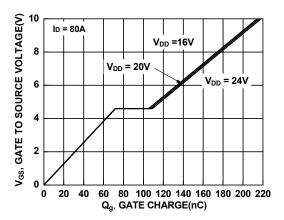


Figure 16. Gate Charge vs. Gate to Source Voltage





TRADEMARKS

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

 $\begin{array}{lll} \mathsf{AccuPower^{TM}} & & \mathsf{F-PFS^{TM}} \\ \mathsf{Awinda}^{\$} & & \mathsf{FRFET}^{\$} \\ \end{array}$

AX-CAP®* Global Power ResourceSM
BitSiC™ GreenBridge™
Build it Now™ Green FPS™

CorePLUS™ Green FPS™ e-Series™

DEUXPEED® Marking Small Speakers Sound Louder

Dual Cool™ and Better™

EcoSPARK® MegaBuck™

EfficentMax™ MICROCOUPLER™

MISSETTIME

MISS

ESBC™ MicroFET™
MicroPak™
MicroPak™
MicroPak2™
Fairchild® MillerDrive™
Fairchild Semiconductor® MotionMax™

FACT Quiet Series™ MotionGrid®
FACT® MTi®
FAST® MTx®
FastvCore™ MVN®
FETBench™ mWSaver®
FPS™ OptoHiT™

PowerTrench[®] PowerXS™

Programmable Active Droop™

QFET[®] QS™ Quiet Series™ RapidConfigure™

Saving our world, 1mW/W/kW at a time™

SignalWise™ SmartMax™ SMART START™

Solutions for Your Success™

SPM[®]
STEALTH™
SuperFET®
SuperSOT™-3
SuperSOT™-6
SuperSOT™-8
SupreMOS®
SyncFET™
Sync-Lock™

SYSTEM ®*
GENERAL
TinyBoost®
TinyCalc™
TinyLogic®
TINYOPTO™
TinyPower™
TinyPWM™
TinyPWM™
TinyPWIre™
TranSiC™
TriFault Detect™
TRUECURRENT®*

WE SENDES*
UHC®
UHTA FRFET™
UniFET™
VCX™
VisualMax™
VoltagePlus™
XS™
XS™
Xsens™
仙童™

μSerDes™

*Trademarks of System General Corporation, used under license by Fairchild Semiconductor.

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. TO OBTAIN THE LATEST, MOST UP-TO-DATE DATASHEET AND PRODUCT INFORMATION, VISIT OUR WEBSITE AT http://www.fairchildsemi.com. Fairchild does not assume any Liability Arising out of the Application or use of any Product or Circuit Described Herein; Neither does it convey any License under its patent rights, nor the rights of others. These specifications do not expand the terms of Fairchild's Worldwide Terms and Conditions, Specifically the Warranty Therein, Which covers these products.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used here in:

- Life support devices or systems are devices or systems which, (a) are
 intended for surgical implant into the body or (b) support or sustain life,
 and (c) whose failure to perform when properly used in accordance with
 instructions for use provided in the labeling, can be reasonably
 expected to result in a significant injury of the user.
- A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

ANTI-COUNTERFEITING POLICY

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, www.Fairchildsemi.com, under Sales Support.

Counterfeiting of semiconductor parts is a growing problem in the industry. All manufactures of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed application, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handing and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address and warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification Product Status		Definition
Advance Information Formative / In Design		Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

Rev. 171

AMEYA360 Components Supply Platform

Authorized Distribution Brand:

























Website:

Welcome to visit www.ameya360.com

Contact Us:

> Address:

401 Building No.5, JiuGe Business Center, Lane 2301, Yishan Rd Minhang District, Shanghai , China

> Sales:

Direct +86 (21) 6401-6692

Email amall@ameya360.com

QQ 800077892

Skype ameyasales1 ameyasales2

Customer Service :

Email service@ameya360.com

Partnership :

Tel +86 (21) 64016692-8333

Email mkt@ameya360.com